ABSTRACT

A resin composition which can be used to form a prepreg having sufficient flexibility to prevent cracking from occurring therein is provided. Further, a prepreg having sufficient flexibility to prevent cracking from occurring, a prepreg having excellent workability even in the case where the resin composition in the prepreg is in an uncured state, and a laminate provided with such a prepreg are also provided. The resin composition is used to form a sheet-shaped prepreg by impregnating a base material with the resin composition, and the composition comprises a first thermosetting resin, a second thermosetting resin having a lower weight average molecular weight than that of the first thermosetting resin, a curing agent, and a filler. The prepreg is formed by impregnating a base sheet material with the resin composition described above. The laminate is formed by laminating a metallic foil on the prepreg and then molding them by heating under pressure. A semiconductor package is manufactured by mounting an IC chip on a prepreg on which the metallic foil has been laminated.